

25 Gbps 1310/1550 nm PIN

MI7D-7020

Part Number: MI7D-7020

Applications: 25 Gbps

Absolute Maximum Ratings (T = 25°C):

Parameter	Symbol	Unit	Value	Note
Forward Current	I _F	mA	10	
Reverse Voltage	V _R	V	20	
Die-Attach Temperature		°C	330	60 Seconds Max
Operating Temperature	T _{op}	°C	-40 to 90	
Storage Temperature	T _{stg}	°C	-40 to +100	

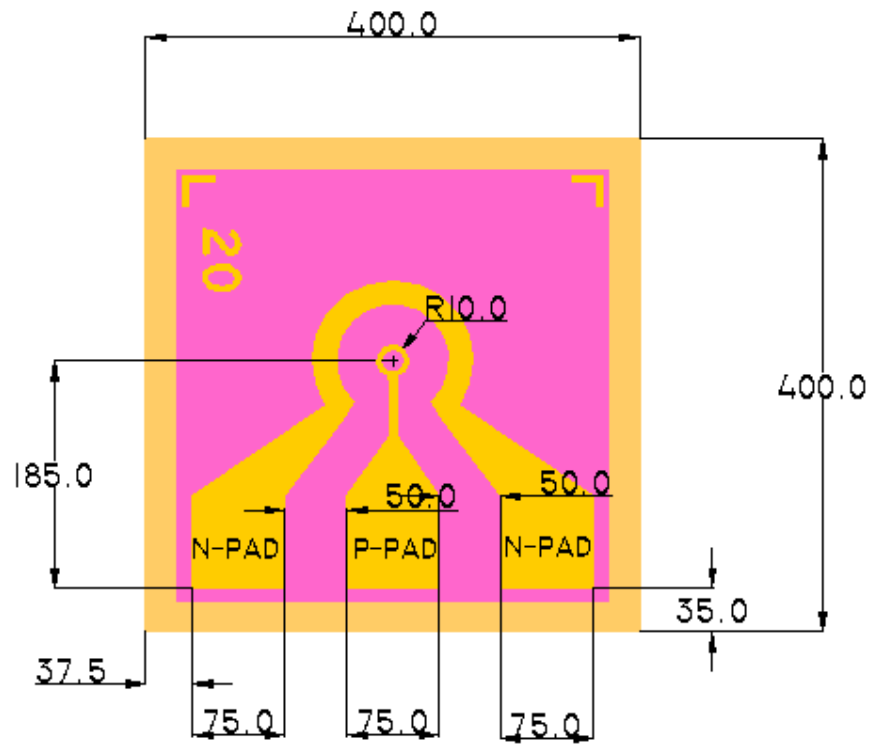


Electro-optical Characteristics (T = 25°C, unless noted otherwise):

Parameter	Symbol	Unit	Min.	Typ.	Max.	Test Condition
Aperture	D	μm	18	20	22	
Responsivity	R	A/W	0.6	0.8		λ = 1310 nm
Dark Current	I _D	nA		10	50	V _R = 5 V
Breakdown Voltage	V _B	V	20			I _R = 10 μA
Capacitance	C	pF		0.08	0.10	V _R = 5 V f = 1 MHz
Cut-off Frequency	f _c	GHz		22		V _R = 5 V R _L = 50Ω

Chip configuration:

1. Top side 50Ω coplanar GSG contact pads.
2. Dimension: 400 μm (width) x 400 μm (length) x 130 μm (thickness)
Tolerance: +/-12.5μm
3. Bond pad size: 75 x 75 μm square



Unit: um

* Specifications are subject to change without notice.
 * Screening per customer-specified reject limits is available.